



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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Features

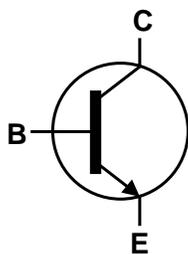
- $BV_{CEO} > 45V$
- $I_C = 3A$ High Continuous Collector Current
- $I_{CM} = 6A$ Peak Pulse Current
- High Gain Device $>400 @1A$
- $R_{CE(SAT)} = 77m\Omega$ for Low Equivalent On-Resistance
- h_{FE} Specified Up to 6A for a High Gain Hold Up

Mechanical Data

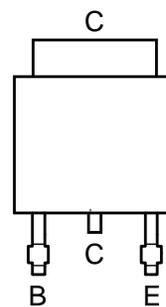
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 
- Weight: 0.34 grams (Approximate)

Applications

- DC-DC Converters
- Power Switches
- IGBT & MOSFET Gate Drivers
- Motor Control
- Automotive Circuits
- Siren Drivers



Equivalent Circuit



Package Pin

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	BV _{CBO}	60	V
Collector-Emitter Voltage	BV _{CEO}	45	V
Emitter-Base Voltage	BV _{EBO}	7	V
Continuous Collector Current	I _C	3	A
Peak Pulse Current	I _{CM}	6	A
Base Current	I _B	0.5	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

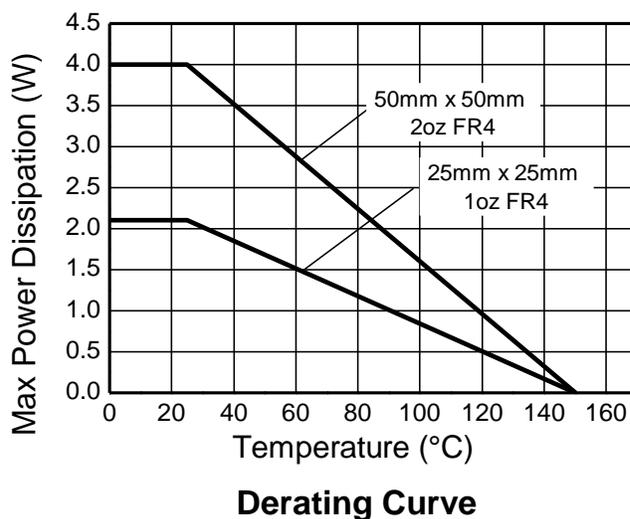
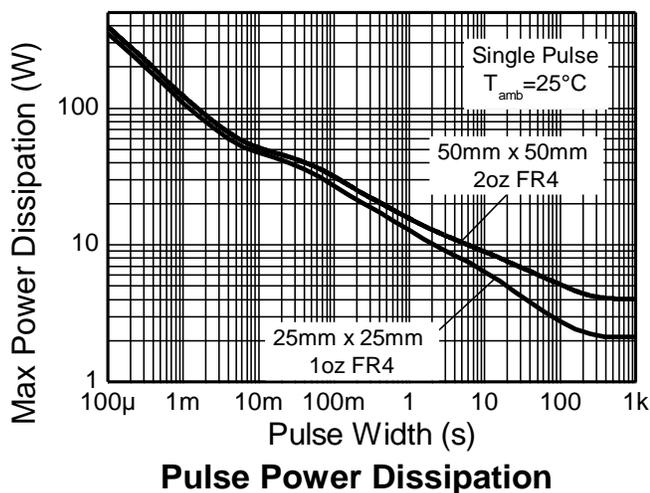
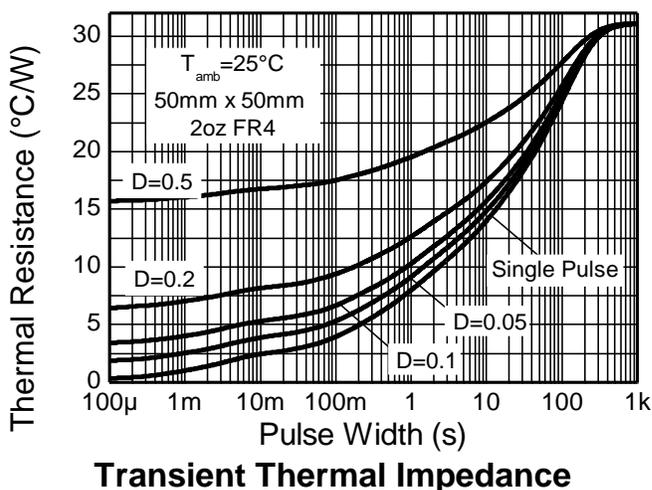
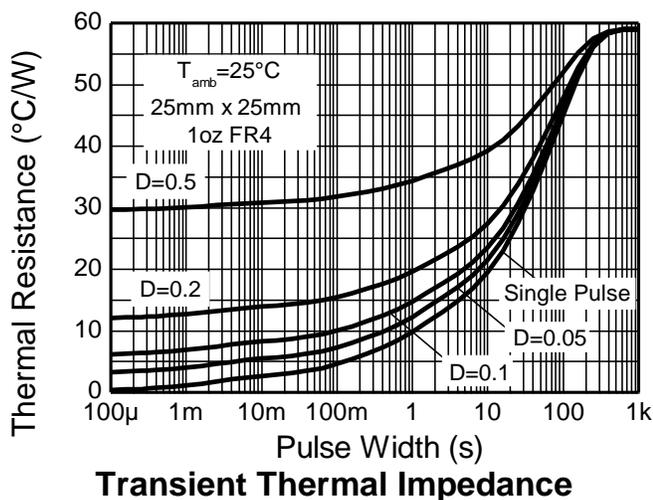
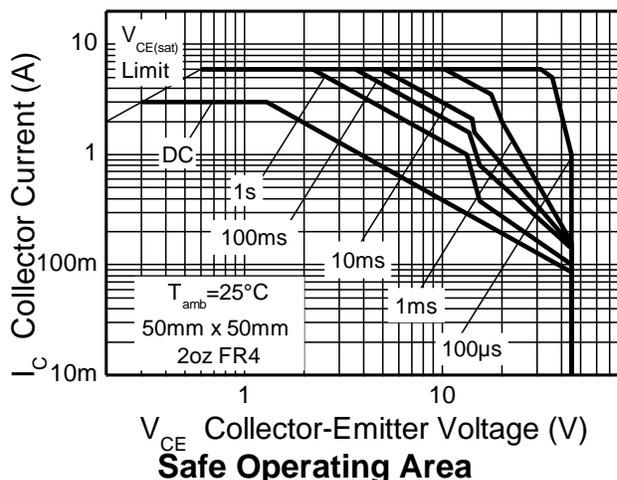
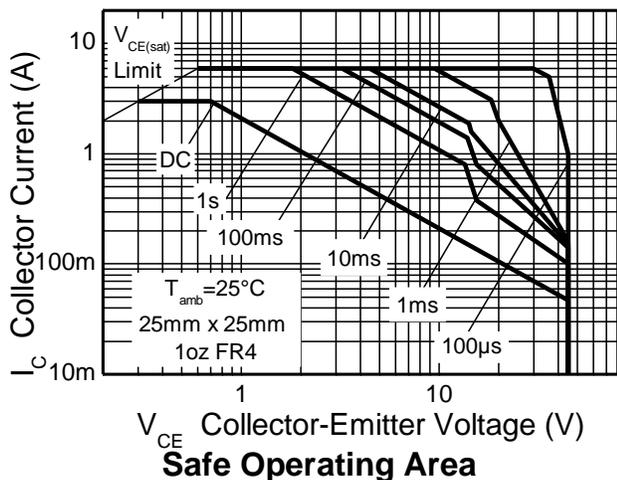
Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	(Note 6)	4.0
		(Note 7)	3.4
		(Note 8)	2.1
		(Note 9)	1.6
Thermal Resistance, Junction to Ambient Air	R _{θJA}	(Note 6)	32
		(Note 7)	36
		(Note 8)	59
		(Note 9)	80
Thermal Resistance, Junction to Leads	R _{θJL}	3	°C/W
Thermal Resistance, Junction to Case	R _{θJC}	14.6	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 12)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted with the exposed collector pad on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 7. Same as Note (6), except mounted on 25mm x 25mm 2oz copper.
 8. Same as Note (6), except mounted on 25mm x 25mm 1oz copper.
 9. Same as Note (6), except mounted on minimum recommended pad (MRP) layout.
 10. Thermal resistance from junction to solder-point (on the exposed collector pad).
 11. Thermal resistance from junction to the top of the case.
 12. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

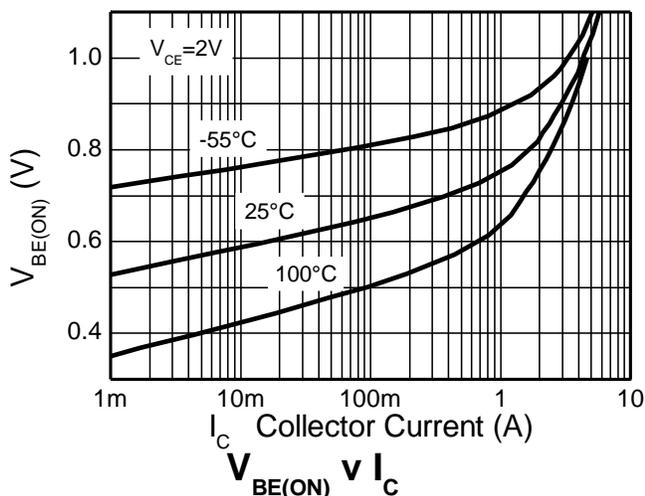
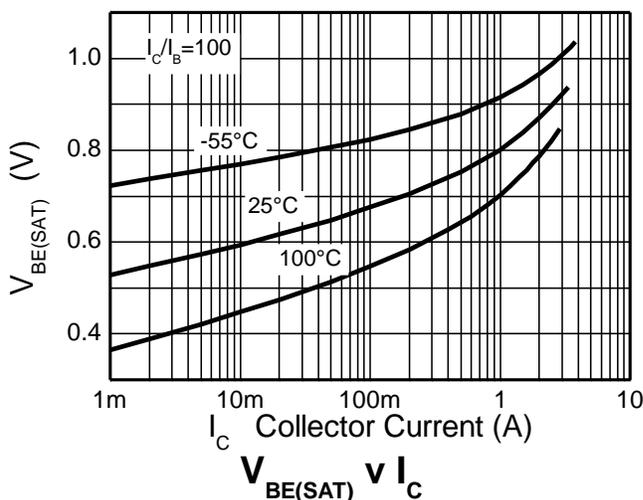
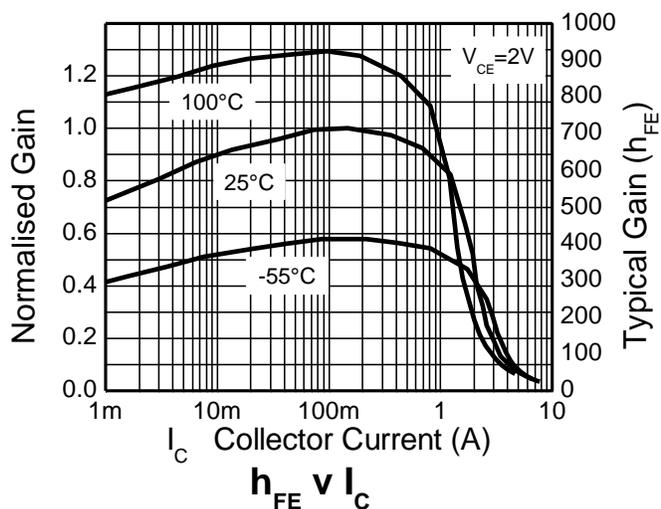
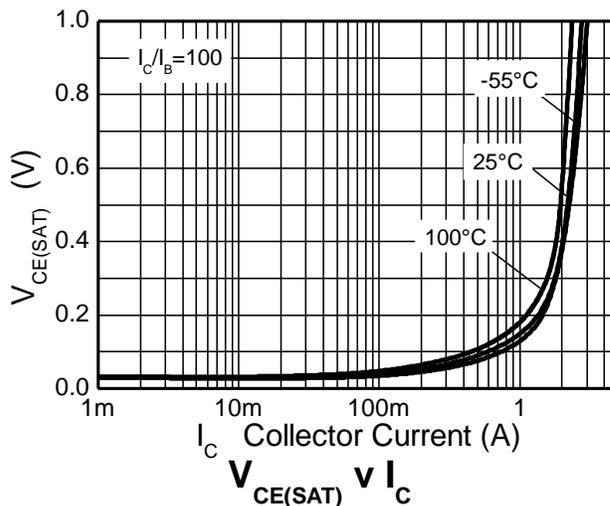
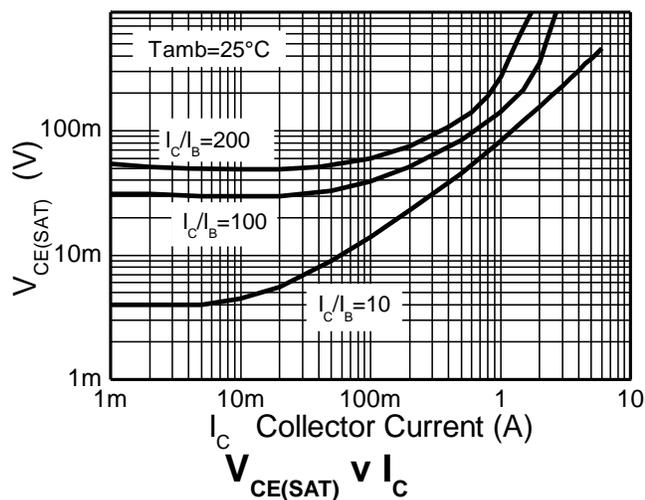


Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

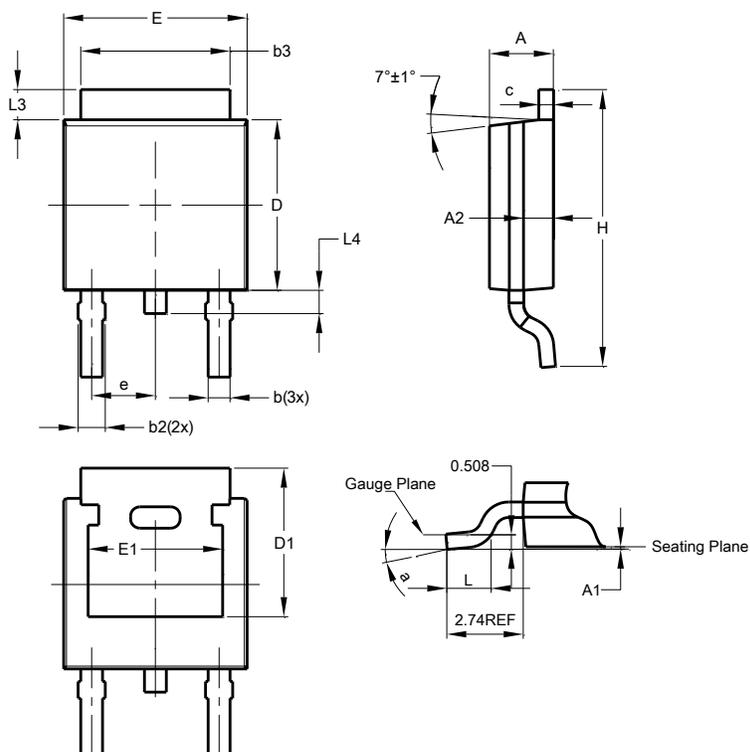
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	60	145	—	V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 13)	BV_{CEO}	45	65	—	V	$I_C = 10\text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	7	8.2	—	V	$I_E = 100\mu\text{A}$
Collector Cutoff Current	I_{CBO}	—	<1	20	nA	$V_{CB} = 35\text{V}$
Collector Cutoff Current	I_{CES}	—	<1	20	nA	$V_{CE} = 35\text{V}$
Emitter Cutoff Current	I_{EBO}	—	<1	20	nA	$V_{EB} = 5.6\text{V}$
Collector-Emitter Saturation Voltage (Note 13)	$V_{CE(SAT)}$	—	50	85	mV	$I_C = 0.1\text{A}, I_B = 0.5\text{mA}$
			240	360		$I_C = 1\text{A}, I_B = 5\text{mA}$
			210	320		$I_C = 2\text{A}, I_B = 40\text{mA}$
			230	350		$I_C = 3\text{A}, I_B = 150\text{mA}$
Base-Emitter Saturation Voltage (Note 13)	$V_{BE(SAT)}$	—	1.0	1.2	V	$I_C = 3\text{A}, I_B = 150\text{mA}$
Base-Emitter Turn-On Voltage (Note 13)	$V_{BE(ON)}$	—	0.9	1.1	V	$I_C = 3\text{A}, V_{CE} = 2\text{V}$
DC Current Gain (Note 13)	h_{FE}	—	500	700	—	$I_C = 100\text{mA}, V_{CE} = 2\text{V}$
			400	600		$I_C = 1\text{A}, V_{CE} = 2\text{V}$
			150	350		$I_C = 2\text{A}, V_{CE} = 2\text{V}$
			60	120		$I_C = 3\text{A}, V_{CE} = 2\text{V}$
Current Gain-Bandwidth Product	f_T	150	—	—	MHz	$I_C = 50\text{mA}, V_{CE} = 5\text{V}, f = 50\text{MHz}$
Output Capacitance	C_{OBO}	—	16	—	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$
Turn-On Time	t_{ON}	—	33	—	ns	$I_C = 500\text{mA}, V_{CC} = 10\text{V}$,
Turn-Off Time	t_{OFF}	—	1,300	—	ns	$I_{B1} = -I_{B2} = 50\text{mA}$

 Note: 13. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

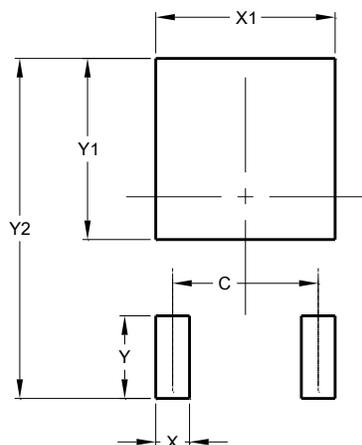


Package Outline Dimensions

TO252 (DPAK)


TO252 (DPAK)			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	-	-
e	-	-	2.286
E	6.45	6.70	6.58
E1	4.32	-	-
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	-
All Dimensions in mm			

Suggested Pad Layout

TO252 (DPAK)


Dimensions	Value (in mm)
C	4.572
X	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700